

Freescale USB Stack v3.2.0 Release Notes

PRODUCT:	Freescale USB Stack
PRODUCT VERSION:	3.2.0
DESCRIPTION:	Freescale USB Stack, version 3.2.0
RELEASE DATE:	March 15 th , 2012





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1 Read Me First

This release note documents the Freescale USB Stack version 3.2.0 released for Freescale ColdFire, HCS08 and Kinetis ARM® CortexM4 microcontroller families.

1.1 Requirements

1.1.1 Development Tools

This Freescale USB Stack Release was compiled and tested with the following development tools:

- CodeWarrior Development Studio for Microcontrollers Version 10.2
 - Support available for Kinetis, ColdFire and HCS08 devices
- IAR Embedded Workbench for ARM Version 6.30
 - Support available for Kinetis ARM® CortexM4 devices

1.1.2 Desktop System Requirements

The system requirements are defined by the development tools requirements. There are no special host system requirements for hosting the Freescale USB Stack distribution itself.

Minimum PC configuration:

As required by Development and Build Tools

Recommended PC configuration:

2 GHz processor – 2 GB RAM - 2 GB free disk space.

Software requirements:

OS: As required by Development and Build tools (Windows XP SP2 or later)



1.1.3 Embedded Target Platforms Requirements

The Freescale USB Stack in this release supports the evaluation boards mentioned below. There are no special requirements for the target hardware which would be out of scope of what each board requires for its operation (power supply, cabling, jumper settings etc). More details about board-specific setup for USB operation are available in the "USBUG.pdf" document.

Evaluation boards supported:

Kinetis ARM® Cortex M4

- TWR-K40X256 Evaluation Board
- TWR-K60N512 Evaluation Board
- TWR-K53N512 Evaluation Board
- TWR-K70FN1M Evaluation Board
- TWR-K20DX50 Evaluation Board
- TWR-K40D72M Evaluation Board
- TWR-K20D72M Evaluation Board

ColdFire V1

- TWR-MCF51JE Evaluation Board
- TWR-MCF51MM Evaluation Board
- TWR-MCF51JF Evaluation Board
- EVB51JM128 Evaluation Board
- DEMOJM Evaluation Board with MCF51JM128 Flexis daughter card

ColdFire V2

- M52221 DEMO Evaluation Board
- M52259EVB Evaluation Board
- M52259DEMOKIT Evaluation Board
- TWR-MCF52259 Evaluation Board
- M52277EVB Evaluation Board

HCS08

- TWR-S08MM128 Evaluation Board
- TWR-S08JE128 Evaluation Board
- DEMOJM Evaluation Board with MC9S0851JM16 Flexis daughter card
- DEMOJM Evaluation Board with MC9S0851JS16 Flexis daughter card
- DEMOJM Evaluation Board with MC9S0851JM60 Flexis daughter card



2 What Is New?

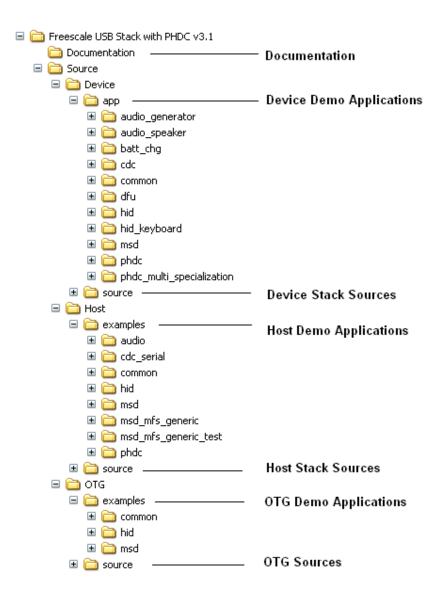
This section describes the major changes and new features implemented in this maintenance release.

- Kinetis K70 USB high speed device, Enhanced Host Control Interface (EHCI) and high speed USB On-The-Go support on the TWR-K70FN1M plus TWR-SER2 board setup
- Kinetis K20 and K40 72MHz devices on TWR-K40D72M and TWR-K20D72M boards support in the stack and applications
- Kinetis K70 USB full speed applications on the IAR Embedded Workbench IDE



3 Release Contents

This section gives an overview about the release folder structure.





4 Known Issues and Limitations

- Because of dynamic memory allocation needs, the limited SRAM available on some devices might not be sufficient to run some host and On-The-Go applications. Also, memory usage and heap management differences may appear depending on the tool chain (IDE) used.
- Because the TWR-K20DX50 board has the D+ and D- USB lines hardwired to the on-board micro-USB connector, the OTG and DCD (battery charging) support has not been tested using a MAX3353 charge pump circuit. The OTG and DCD support in the applications included in this package is based on designs which include a MAX3353 circuit, which is used for VBUS detection purposes.
- The USB high speed device and EHCI support on K70 requires the TWR-SER2 peripheral board for the SMSC USB3300 ULPI transceiver circuit mounted on it. This board should be used in a TWR setup with the TWR-K70FN1M controller tower board.



5 Device, Host and On-The-Go Supported Platforms Overview

This release supports the USB stack and example applications for USB classes for a variety of HCS08, ColdFire and Kinetis microcontrollers. The matrices of supported demo applications on devices and IDEs are found below.

5.1 DEVICE

5.1.1 HCS08

DEVICE	PART				
CLASS	MC9S08JE128	MC9S08JS16	MC9S08JM60	MC9S08JM16	MC9S08MM128
CDC	CW 6.3, CW 10.1				
HID	CW 6.3, CW 10.1				
Audio	CW 6.3, CW 10.1	N/A	CW 6.3, CW 10.1	N/A	CW 6.3, CW 10.1
Battery Charging	N/A	N/A	N/A	N/A	N/A
DFU	CW 6.3, CW 10.1				
MSD	CW 6.3, CW 10.1	N/A	CW 6.3, CW 10.1	N/A	CW 6.3, CW 10.1
PHDC	CW 6.3, CW 10.1				

5.1.2 ColdFire

DEVICE	PART						
CLASS	MCF51JE256	MCF51JM128	MCF51MM256	MCF51JF128	MCF52259	MCF52221	MCF52277
CDC	CW 6.3, CW 10.1	CW 6.3, CW 10.1	CW 6.3, CW 10.1	CW 10.1	CW 7.2, CW 10.1	CW 7.2, CW 10.1	CW 7.2, CW 10.1
HID	CW 6.3, CW 10.1	CW 6.3, CW 10.1	CW 6.3, CW 10.1	CW 10.1	CW 7.2, CW 10.1	CW 7.2, CW 10.1	CW 7.2, CW 10.1
Audio	CW 6.3, CW 10.1	CW 6.3, CW 10.1	CW 6.3, CW 10.1	CW 10.1	CW 7.2, CW 10.1	CW 7.2, CW 10.1	N/A
Battery							
Charging	N/A	N/A	N/A	CW 10.1	N/A	N/A	N/A
DFU	CW 6.3, CW 10.1	CW 6.3, CW 10.1	CW 6.3, CW 10.1	CW 10.1	CW 7.2, CW 10.1	CW 7.2, CW 10.1	CW 7.2, CW 10.1
MSD	CW 6.3, CW 10.1	CW 6.3, CW 10.1	CW 6.3, CW 10.1	CW 10.1	CW 7.2, CW 10.1	CW 7.2, CW 10.1	CW 7.2, CW 10.1
PHDC	CW 6.3, CW 10.1	CW 6.3, CW 10.1	CW 6.3, CW 10.1	CW 10.1	CW 7.2, CW 10.1	CW 7.2, CW 10.1	CW 7.2, CW 10.1



5.1.3 Kinetis

DEVICE	K20	K40	K50	K60	K70
CLASS	PK20X128VLH MK20DX256VLL7	MK40N512VMD100 MK40DX256VLL7	MK53N512CMD100	MK60N512VMD100	PK70FN1M0VMJ12
CDC	CW 10.2, IAR EW 6.3	CW 10.1, IAR EW 6.2	CW 10.1, IAR EW 6.2	CW 10.1, IAR EW 6.2	CW 10.2, IAR EW 6.3
HID	CW 10.2, IAR EW 6.3	CW 10.1, IAR EW 6.2	CW 10.1, IAR EW 6.2	CW 10.1, IAR EW 6.2	CW 10.2, IAR EW 6.3
Audio	CW 10.2, IAR EW 6.3	CW 10.1, IAR EW 6.2	CW 10.1, IAR EW 6.2	CW 10.1, IAR EW 6.2	CW 10.2, IAR EW 6.3
Battery Charging	CW 10.2, IAR EW 6.3	CW 10.1, IAR EW 6.2	CW 10.1, IAR EW 6.2	CW 10.1, IAR EW 6.2	CW 10.2, IAR EW 6.3
DFU	CW 10.2, IAR EW 6.3	CW 10.1, IAR EW 6.2	CW 10.1, IAR EW 6.2	CW 10.1, IAR EW 6.2	CW 10.2, IAR EW 6.3
MSD	CW 10.2, IAR EW 6.3	CW 10.1, IAR EW 6.2	CW 10.1, IAR EW 6.2	CW 10.1, IAR EW 6.2	CW 10.2, IAR EW 6.3
PHDC	CW 10.2, IAR EW 6.3	CW 10.1, IAR EW 6.2	CW 10.1, IAR EW 6.2	CW 10.1, IAR EW 6.2	CW 10.2, IAR EW 6.3

5.2 HOST

5.2.1 HCS08

No host applications are available for HCS08 architectures due to memory limitations.

5.2.2 ColdFire

HOST	PART						
CLASS	MCF51JE256	MCF51JM128	MCF51MM256	MCF51JF128	MCF52259	MCF52221	MCF52277
CDC	CW 6.3, CW 10.1	CW 6.3, CW 10.1	CW 6.3, CW 10.1	CW 10.1	CW 7.2, CW 10.1	CW 7.2, CW 10.1	CW 7.2, CW 10.1
HID	CW 6.3, CW 10.1	CW 6.3, CW 10.1	CW 6.3, CW 10.1	CW 10.1	CW 7.2, CW 10.1	CW 7.2, CW 10.1	CW 7.2, CW 10.1
Audio	CW 6.3, CW 10.1	N/A	CW 6.3, CW 10.1	CW 10.1	CW 7.2, CW 10.1	CW 7.2, CW 10.1	N/A
FAT FS	CW 6.3, CW 10.1	CW 6.3, CW 10.1	CW 6.3, CW 10.1	CW 10.1	CW 7.2, CW 10.1	CW 7.2, CW 10.1	N/A
MSD	CW 6.3, CW 10.1	CW 6.3, CW 10.1	CW 6.3, CW 10.1	CW 10.1	CW 7.2, CW 10.1	CW 7.2, CW 10.1	CW 7.2, CW 10.1
PHDC	CW 6.3, CW 10.1	CW 6.3, CW 10.1	CW 6.3, CW 10.1	CW 10.1	CW 7.2, CW 10.1	CW 7.2, CW 10.1	CW 7.2, CW 10.1



5.2.3 Kinetis

HOST	K20	K40	K50	K60	K70
CLASS	PK20X128VLH MK20DX256VLL7	MK40N512VMD100 MK40DX256VLL7	MK53N512CMD100	MK60N512VMD100	PK70FN1M0VMJ12
CDC	CW 10.2, IAR EW 6.3	CW 10.1, IAR EW 6.2	CW 10.1, IAR EW 6.2	CW 10.1, IAR EW 6.2	CW 10.2, IAR EW 6.3
HID	CW 10.2, IAR EW 6.3	CW 10.1, IAR EW 6.2	CW 10.1, IAR EW 6.2	CW 10.1, IAR EW 6.2	CW 10.2, IAR EW 6.3
Audio	CW 10.2, IAR EW 6.3	CW 10.1, IAR EW 6.2	CW 10.1, IAR EW 6.2	CW 10.1, IAR EW 6.2	CW 10.2, IAR EW 6.3
FAT FS	CW 10.2, IAR EW 6.3	CW 10.1, IAR EW 6.2	CW 10.1, IAR EW 6.2	CW 10.1, IAR EW 6.2	CW 10.2, IAR EW 6.3
MSD	CW 10.2, IAR EW 6.3	CW 10.1, IAR EW 6.2	CW 10.1, IAR EW 6.2	CW 10.1, IAR EW 6.2	CW 10.2, IAR EW 6.3
PHDC	CW 10.2, IAR EW 6.3	CW 10.1, IAR EW 6.2	CW 10.1, IAR EW 6.2	CW 10.1, IAR EW 6.2	CW 10.2, IAR EW 6.3

5.3 OTG

5.4 Kinetis

OTG	K20	K40	K50	K60	K70
CLASS	PK20X128VLH MK20DX256VLL7	MK40N512VMD100 MK40DX256VLL7	MK53N512CMD100	MK60N512VMD100	PK70FN1M0VMJ12
HID	CW 10.2, IAR EW 6.3	CW 10.1, IAR EW 6.2	CW 10.1, IAR EW 6.2	CW 10.1, IAR EW 6.2	CW 10.2, IAR EW 6.3
MSD	CW 10.2, IAR EW 6.3	CW 10.1, IAR EW 6.2	CW 10.1, IAR EW 6.2	CW 10.1, IAR EW 6.2	CW 10.2, IAR EW 6.3

5.5 ColdFire

OTG	PART	
CLASS	MCF51JF128	MCF51JM128
HID	CW 10.1	CW 10.1
MSD	CW 10.1	CW 10.1